

研究方向

◆三五族化合物半導體材料 AlGaAs/GaAs, InGaP/GaAs, InAlGaP/GaAs, InAlAs/InGaAs/InP, AlGaN/GaN以及 InAlAsSb/InP等異質材料系統

◆微波元件:

- (a) 實空間傳輸元件 (Real-Space Transfer Devices)
- (b) 高電子移動率電晶體 (High-Electron Mobility Transistor)
- (c) 異質接面雙極性電晶體 (Heterojunction Bipolar Transistor)

◆光電元件:

- (a) 發光二極體 (Light-Emitting Diode)
- (b) 光檢測器 (Photodetector)

研究成果

20 nm n ⁺ -In _{0.5} Ga _{0.5} As	δ-doping
25 nm i-In _{0.45} Al _{0.55} As Schottky layer	
4 nm i-In _{0.45} Al _{0.45} Al _{0.55} As spacer layer	
20 nm i-In _{0.5} Ga _{0.5} As channel layer	
150 nm i-In _{0.45} Al _{0.55} As Barrier/Buffer	
500 nm i-In _x Al _{1-x} As (x=0→0.475) Metamorphic buffer layer	
S. I. GaAs Substrate	

Fig. Schematic representations of the MHEMT under trial.

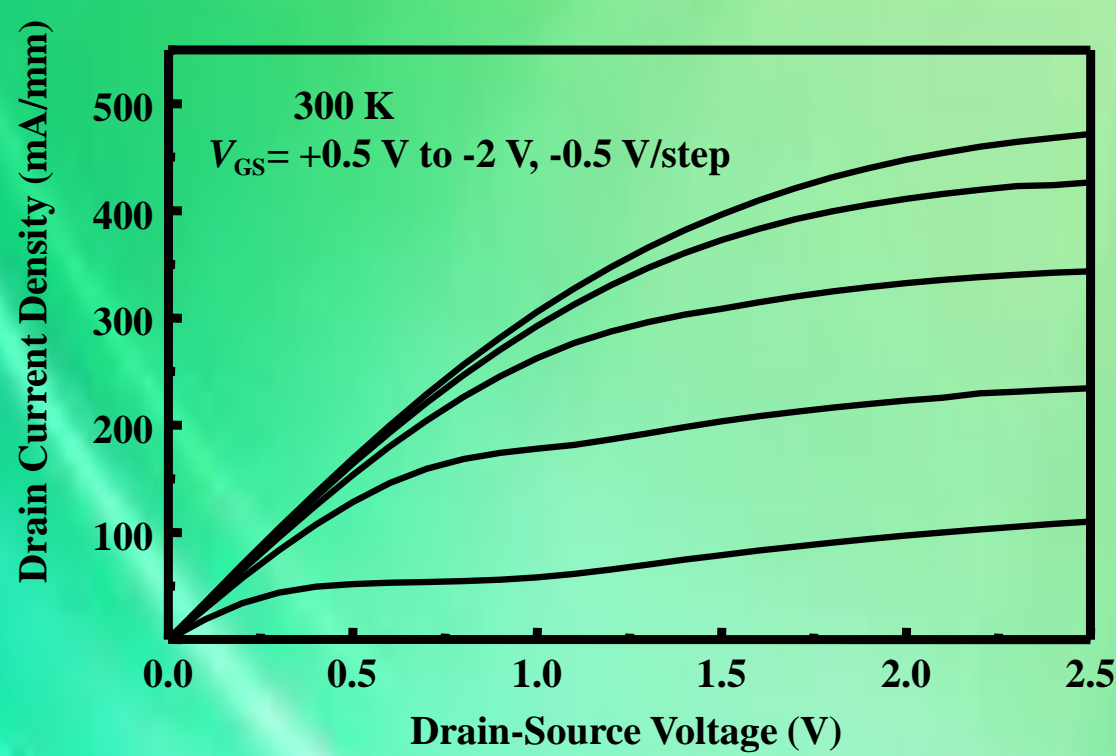


Fig. 1 Common-source $I_D - V_{DS}$ characteristics.

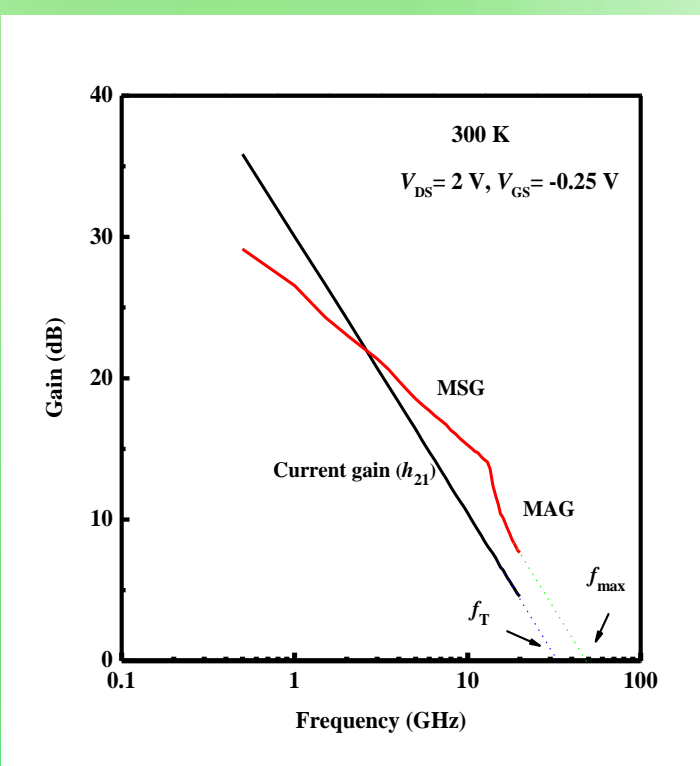


Fig. 2 Frequency-dependence of current gain h_{21} and power gain.

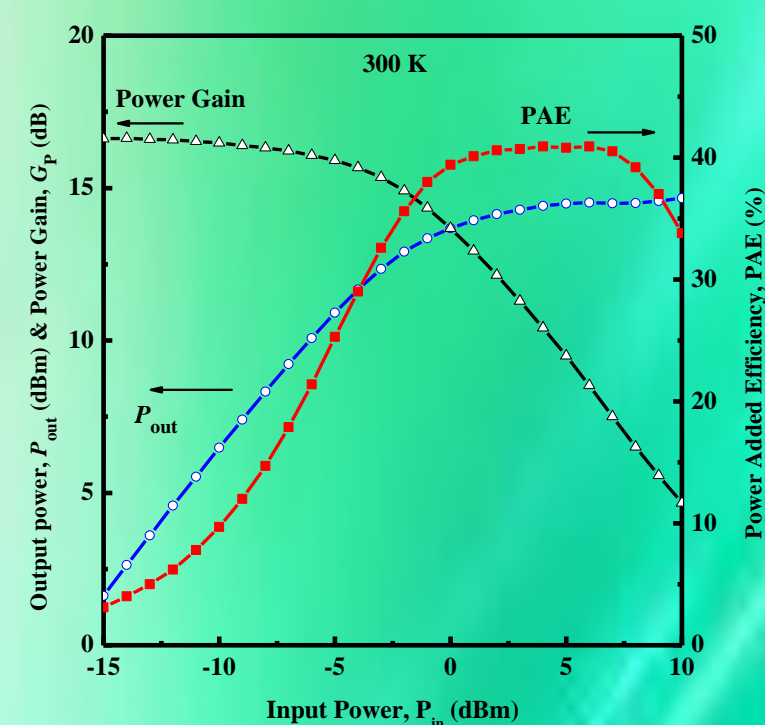


Fig. 3 P_{out} , GP and PAE at 2.4 GHz as functions of input power to the MHEMT at $V_{DS}=2.5$ V.

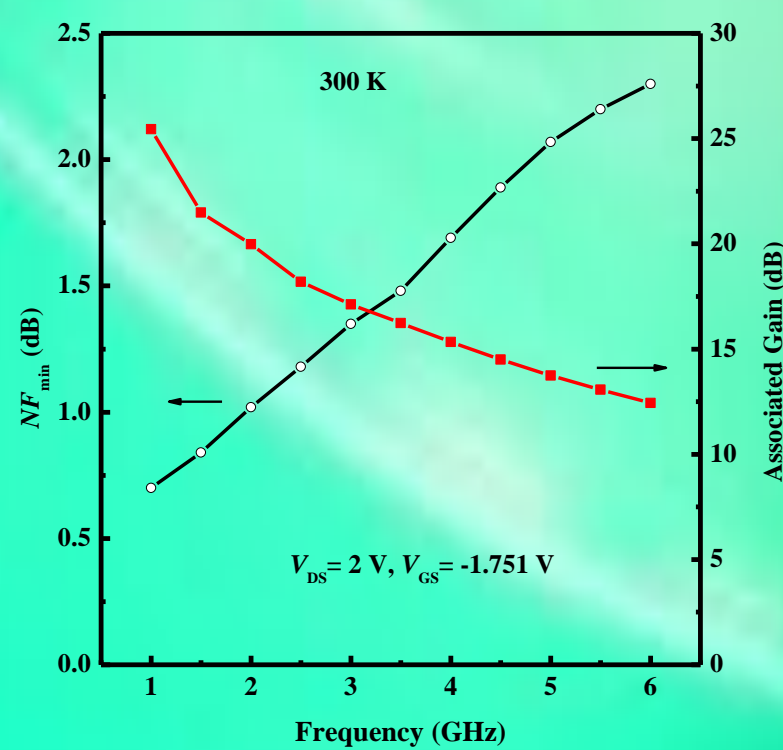


Fig. 4 Minimum noise figure NF_{min} and associated gain versus frequency.

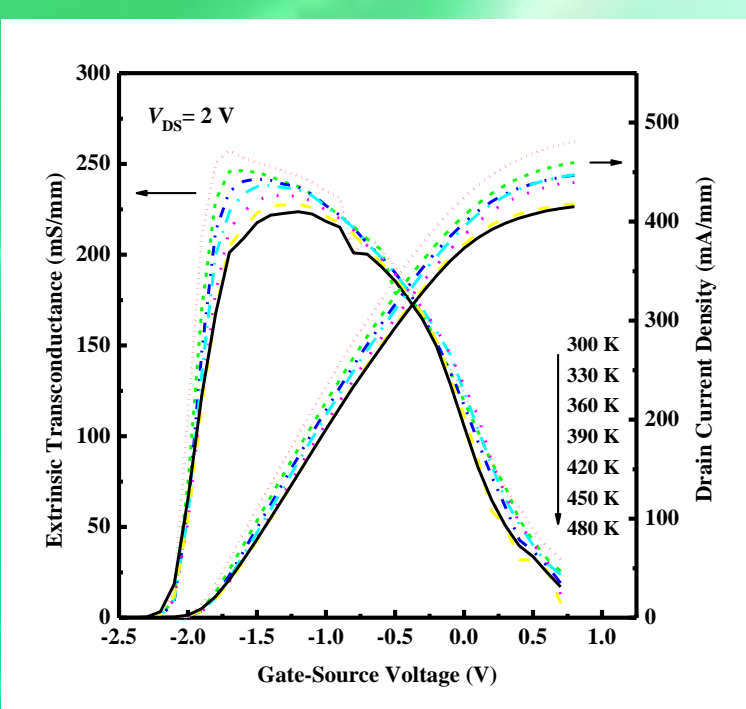


Fig. 5 DC transfer characteristics of the MHEMT at various temperatures.

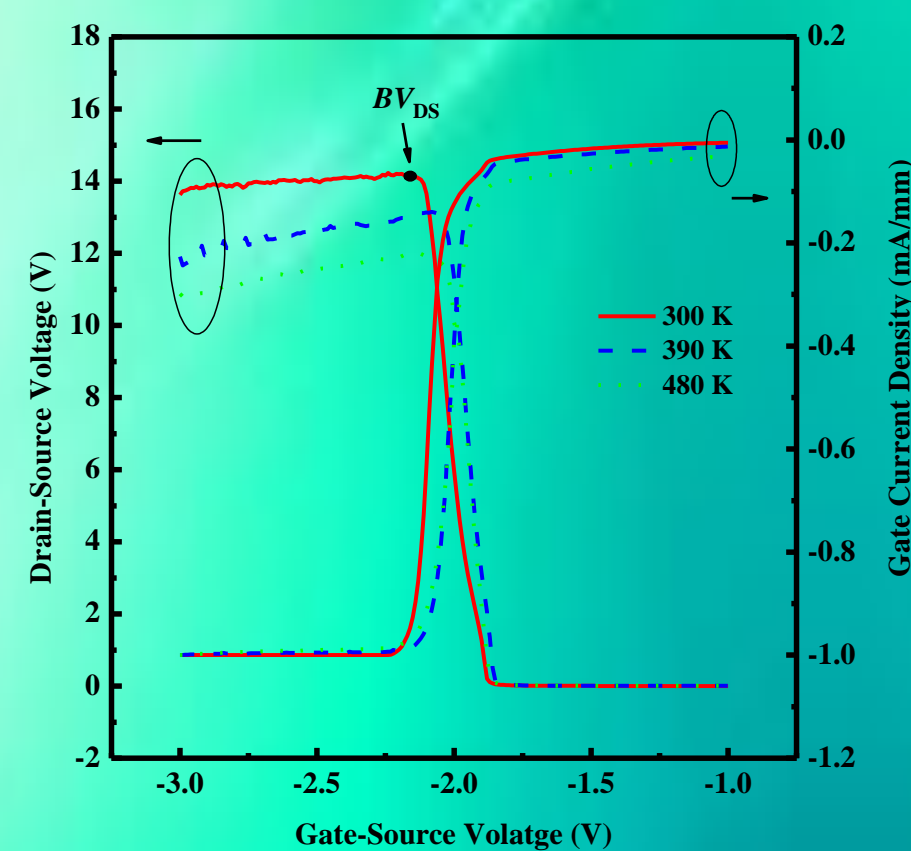


Fig. 6 Drain-current injection scan of MHEMT for $I_D=1$ mA/mm at various temperatures. The peak of the V_{DS} trace marks the drain-source breakdown voltage V_{BDS} .